

WHAT IS CLAIMED IS:

1. A process for manufacturing a flexible printed wiring board, comprising forming a resin coating at least on a metal bump on a metal film having said metal bump, pressing said resin coating on said metal bump, and then etching said resin coating to expose the surface of said metal bump.
2. A process for manufacturing a flexible printed wiring board according to Claim 1 wherein said resin coating is formed on said metal bump and on said metal film.
3. A process for manufacturing a flexible printed wiring board according to Claim 2 wherein said resin coating comprises a lower thermosetting resin coating and an upper thermoplastic resin coating formed on the surface of said lower resin coating.
4. A process for manufacturing a flexible printed wiring board according to Claim 2 wherein a pressure is applied on said metal bump after a resist film resistant to etching with a chemical for etching said resin coating is formed on said resin coating.
5. A process for manufacturing a flexible printed wiring

board according to Claim 3 wherein a pressure is applied on said metal bump after a resist film resistant to etching with a chemical for etching said upper thermoplastic resin coating is formed on said upper thermoplastic resin coating.

6. A process for manufacturing a flexible printed wiring board according to Claim 2 wherein said metal bump is formed by forming a photosensitive mask film on the surface of said metal film, then patterning said mask film by exposure and development, and depositing a metal by plating on the surface of said metal film exposed at the opening of said mask film.

7. A process for manufacturing a flexible printed wiring board according to Claim 3 wherein said metal bump is formed by forming a photosensitive mask film on the surface of said metal film, then patterning said mask film by exposure and development, and depositing a metal by plating on the surface of said metal film exposed at the opening of said mask film.

8. A process for manufacturing a flexible printed wiring board according to Claim 4 wherein said metal bump is formed by forming a photosensitive mask film on the

surface of said metal film, then patterning said mask film by exposure and development, and depositing a metal by plating on the surface of said metal film exposed at the opening of said mask film.

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9. A process for manufacturing a flexible printed wiring board according to Claim 5 wherein said metal bump is formed by forming a photosensitive mask film on the surface of said metal film, then patterning said mask film by exposure and development, and depositing a metal by plating on the surface of said metal film exposed at the opening of said mask film.

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10. A process for manufacturing a flexible printed wiring board according to Claim 2 wherein said pressing of said metal bump comprises at least rotating a roller against said resin coating.

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11. A process for manufacturing a flexible printed wiring board according to Claim 3 wherein said pressing of said metal bump comprises at least rotating a roller against said resin coating.

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12. A process for manufacturing a flexible printed wiring board according to Claim 4 wherein said pressing

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of said metal bump comprises at least rotating a roller against said resin coating.

13. A process according for manufacturing a flexible printed wiring board to Claim 5 wherein said pressing of said metal bump comprises at least rotating a roller against said resin coating.

14. A process for manufacturing a flexible printed wiring board according to Claim 10 wherein said roller is heated during said pressing.

15. A process for manufacturing a flexible printed wiring board according to Claim 11 wherein said roller is heated during said pressing.

16. A process for manufacturing a flexible printed wiring board according to Claim 12 wherein said roller is heated during said pressing.

17. A process for manufacturing a flexible printed wiring board according to Claim 13 wherein said roller is heated during said pressing.

18. A process for manufacturing a flexible printed

wiring board according to Claim 2 wherein a polyamic acid is used as a material for said resin coating.

19. A process for manufacturing a flexible printed wiring board according to Claim 3 wherein a polyamic acid is used as a material for said resin coating.

20. A process for manufacturing a flexible printed wiring board according to Claim 4 wherein a polyamic acid is used as a material for said resin coating.

21. A process for manufacturing a flexible printed wiring board according to Claim 5 wherein a polyamic acid is used as a material for said upper thermoplastic resin coating and/or said lower thermosetting resin coating.

22. A flexible printed wiring board comprising a metal film, a resin coating on said metal film, and a metal bump located in an opening formed in said resin coating, connected at its bottom face to said metal film and having a height greater than the thickness of said resin coating, wherein said resin coating is removed by etching at least at the portion located at an end of said metal bump to expose the end of said metal bump